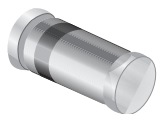


# Material Composition Specification

SOD-80 Case

Pb (lead)-free plating\*



Device average mass . . . . . 28 mg

Fluctuation margin . . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.43%	0.03	Si	7440-21-3	0.11%	0.03	1,071
leadframe	Fe alloy w/ silver plating	56.32%	15.77	Cu	7440-50-8	8.93%	2.5	89,286
				Fe	7439-89-6	23.93%	6.7	239,286
				Ni	7440-02-0	21.07%	5.9	210,714
				Ag	7440-22-4	2.39%	0.67	23,929
encapsulation	glass	40.0%	11.2	SiO <sub>2</sub>	7631-86-9	16.96%	4.75	169,643
				PbO	1314-41-6	23.04%	6.45	230,357
plating*	tin lead process	3.57%	1.0	Sn	7440-31-5	2.86%	0.8	28,571
				Pb	7439-92-1	0.71%	0.2	7,143
	100% tin process	1.36%	1.0	Sn	7440-31-5	3.57%	1.0	35,714

\*Specify Lead-Free when ordering 100% tin (Pb-free) plating.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R1 (9-March 2010)